

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
14 April 2005 (14.04.2005)

PCT

(10) International Publication Number
WO 2005/033352 A3

(51) International Patent Classification⁷: **B05D 1/06**

(21) International Application Number:
PCT/US2004/022143

(22) International Filing Date: 9 July 2004 (09.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/485,912 9 July 2003 (09.07.2003) US

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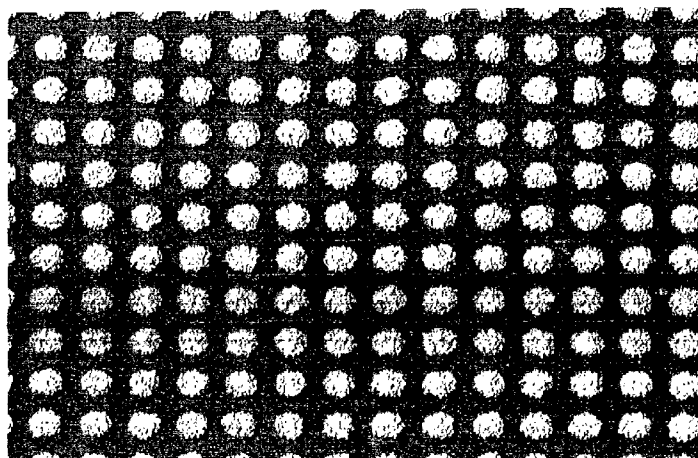
(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— with international search report

[Continued on next page]

(54) Title: DEPOSITION AND PATTERNING PROCESS



(57) Abstract: A method for applying particles in a pattern to a substrate, either directly or by use of an intermediate tool, by electrokinetic or electrostatic means. A method for applying metal particles such as solder metal in a pattern to an electronic device substrate, either directly or by use of an intermediate tool, by electrokinetic or electrostatic means.

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— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

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(88) Date of publication of the international search report:

14 July 2005